



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Teck Kheng Lee

Serial No.: 10/782,270

Filed: February 18, 2004

For: INTERPOSER SUBSTRATE AND  
WAFER SCALE INTERPOSER  
SUBSTRATE MEMBER FOR USE WITH  
FLIP-CHIP CONFIGURED  
SEMICONDUCTOR DICE

Confirmation No.: 4215

Examiner: J. Clark

Group Art Unit: 2815

Attorney Docket No.: 2269-4973.1US  
(00-0593.01/US)

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

12/21/2004  
Date

Signature

Joseph A. Walkowski  
Name (Type/Print)

RESPONSE TO OFFICE ACTION

Mail Stop Amendment  
Commissioner for Patents  
PO Box 1450  
Alexandria, VA 22313-1450

Sir:

The following amendments and remarks are filed in response to the Examiner's remarks in the Office Action mailed September 22, 2004, the three-month shortened statutory period for response to which expires on December 22, 2004.

**A Listing of Claims** begins on page 2 of this paper.

**Remarks** begin on page 7 of this paper.